

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination JIANG ET AL.	
		09/652,216	Examiner	Art Unit 2829
Evan T. Pert		Page 1 of 1		

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-2002/0055246 A1	12-2001	Jiang et al.	438/597
	B	US-6,406,938	06-2002	Rodenbeck et al.	438/108
	C	US-6,061,267	05-2000	Houston, Theodore W.	365/154
	D	US-6,064,116	05-2000	Akram, Salman	257/700
	E	US-5,317,107	05-1994	Osorio, Rolando J.	174/35R
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Shah et al., "Cyanate Ester Die Attach Material For Radiation Hardened Electronic Packages", 3rd International Conference on Adhesive Joining & Coating Technology in Electronic Manufacturing, Binghamton, NY, September 1998., 6 pages.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.